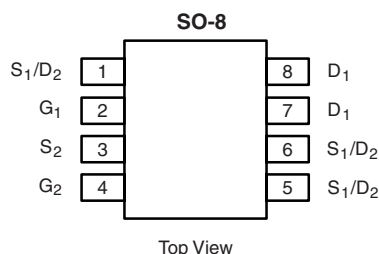


Dual N-Channel 25-V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY				
	V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{a, e}	Q _g (Typ.)
Channel-1	25	0.023 at V _{GS} = 10 V	8.0	5.5
		0.028 at V _{GS} = 4.5 V	8.0	
Channel-2	25	0.023 at V _{GS} = 10 V	8.0	5.5
		0.028 at V _{GS} = 4.5 V	8.0	

SCHOTTKY PRODUCT SUMMARY		
V _{DS} (V)	V _{SD} (V) Diode Forward Voltage	I _F (A) ^a
25	0.43 V at 1.0 A	2.3



Ordering Information: Si4670DY-T1-E3 (Lead (Pb)-free)
Si4670DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

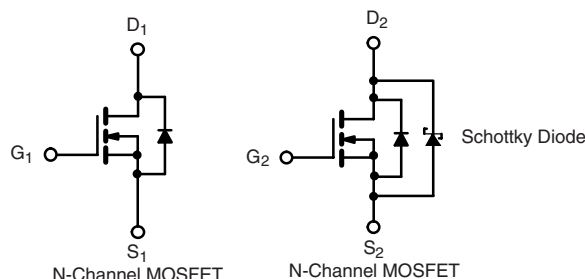
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- PWM Optimized
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE
Available

APPLICATIONS

- Synchronous Buck Converter
- Game Machine
- Notebook



ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted				
Parameter	Symbol	Channel-1	Channel-2	Unit
Drain-Source Voltage	V _{DS}	25	25	V
Gate-Source Voltage	V _{GS}	± 16	± 16	
Continuous Drain Current (T _J = 150 °C)	I _D	8.0 ^e	8.0 ^e	A
		7	7	
		7 ^{b, c}	7 ^{b, c}	
		5.6 ^{b, c}	5.6 ^{b, c}	
Pulsed Drain Current (10 μs Pulse Width)	I _{DM}	30	30	A
Source-Drain Current Diode Current	I _S	2.3	2.3	
		1.5 ^{b, c}	1.5 ^{b, c}	
Maximum Power Dissipation	P _D	2.8	2.8	W
		1.8	1.8	
		1.8 ^{b, c}	1.8 ^{b, c}	
		1.1 ^{b, c}	1.1 ^{b, c}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Channel-1		Channel-2		Unit
		Typ.	Max.	Typ.	Max.	
Maximum Junction-to-Ambient ^{b, d}	R _{thJA}	57	70	57	70	°C/W
Maximum Junction-to-Foot (Drain)	R _{thJF}	36	44	36	44	

Notes:

a. Based on T_C = 25 °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 110 °C/W (Channel-1 and Channel-2).

e. Package limited.

SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	Ch-1	25		V	
		V _{GS} = 0 V, I _D = 250 μA	Ch-2	25			
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = 250 μA	Ch-1		25	mV/°C	
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J	I _D = 250 μA	Ch-1		- 4.7		
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	Ch-1	1		2.2	V
		V _{DS} = V _{GS} , I _D = 250 μA	Ch-2	1		2.2	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 16 V	Ch-1			100	nA
		V _{DS} = 0 V, V _{GS} = ± 16 V	Ch-2			100	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 25 V, V _{GS} = 0 V	Ch-1			0.001	mA
		V _{DS} = 25 V, V _{GS} = 0 V	Ch-2		0.07	0.5	
		V _{DS} = 25 V, V _{GS} = 0 V, T _J = 100 °C	Ch-1			0.025	
		V _{DS} = 25 V, V _{GS} = 0 V, T _J = 100 °C	Ch-2		5	20	
On-State Drain Current ^b	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	Ch-1	20		A	
		V _{DS} ≥ 5 V, V _{GS} = 10 V	Ch-2	20			
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 7 A	Ch-1		0.019	0.023	Ω
		V _{GS} = 10 V, I _D = 7 A	Ch-2		0.019	0.023	
		V _{GS} = 4.5 V, I _D = 6.3 A	Ch-1		0.023	0.028	
		V _{GS} = 4.5 V, I _D = 6.3 A	Ch-2		0.023	0.028	
Forward Transconductance ^b	g _{fs}	V _{DS} = 10 V, I _D = 7 A	Ch-1		23	S	
		V _{DS} = 10 V, I _D = 7 A	Ch-2		23		
Dynamic ^a							
Input Capacitance	C _{iss}	Channel-1 V _{DS} = 13 V, V _{GS} = 0 V, f = 1 MHz	Ch-1		680	pF	
			Ch-2		680		
Output Capacitance	C _{oss}	Channel-2 V _{DS} = 13 V, V _{GS} = 0 V, f = 1 MHz	Ch-1		120		
			Ch-2		180		
Reverse Transfer Capacitance	C _{rss}	Channel-1 V _{DS} = 13 V, V _{GS} = 0 V, f = 1 MHz	Ch-1		55	nC	
			Ch-2		70		
Total Gate Charge	Q _g	V _{DS} = 13 V, V _{GS} = 10 V, I _D = 7 A	Ch-1		12	18	nC
		V _{DS} = 13 V, V _{GS} = 10 V, I _D = 7 A	Ch-2		12	18	
Gate-Source Charge	Q _{gs}	Channel-1 V _{DS} = 13 V, V _{GS} = 4.5 V, I _D = 7 A	Ch-1		5.5	8.5	
			Ch-2		5.5	8.5	
Gate-Drain Charge	Q _{gd}	Channel-2 V _{DS} = 13 V, V _{GS} = 4.5 V, I _D = 7 A	Ch-1		2		
			Ch-2		2		
Gate Resistance	R _g	f = 1 MHz	Ch-1		2.5	Ω	
			Ch-2		3.2		

Notes:

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.



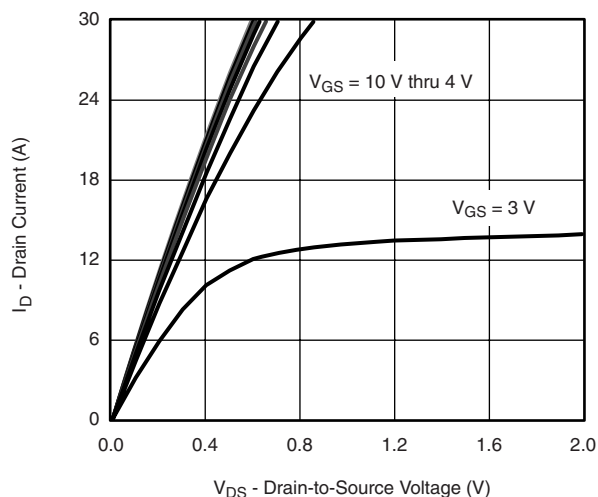
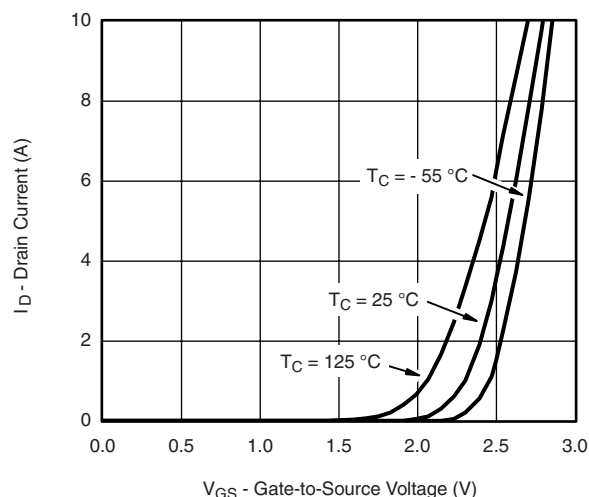
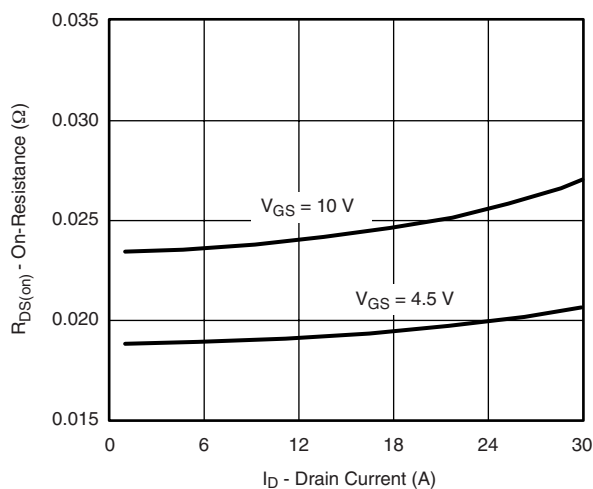
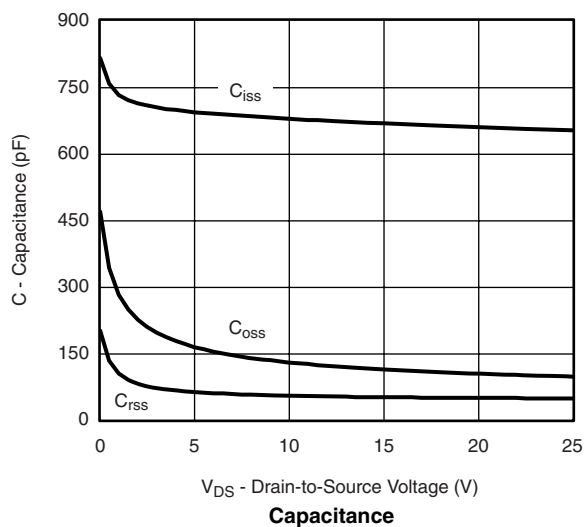
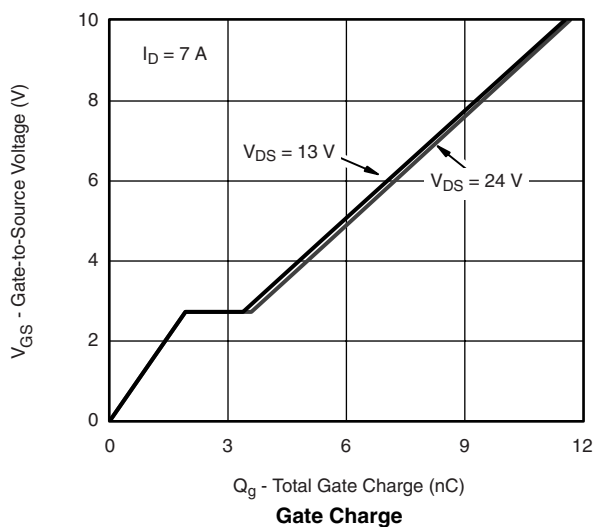
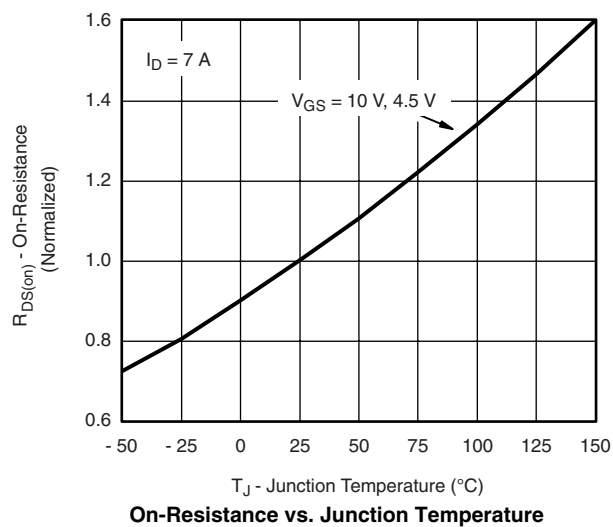
SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted								
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit		
Dynamic ^a								
Turn-On Delay Time	$t_{d(on)}$	Channel-1 $V_{DD} = 13\text{ V}$, $R_L = 2.3\text{ }\Omega$ $I_D \cong 5.6\text{ A}$, $V_{GEN} = 4.5\text{ V}$, $R_g = 1\text{ }\Omega$	Ch-1		15	25	ns	
			Ch-2		15	25		
Rise Time	t_r		Ch-1		50	75		
			Ch-2		50	75		
Turn-Off Delay Time	$t_{d(off)}$	Channel-2 $V_{DD} = 13\text{ V}$, $R_L = 2.3\text{ }\Omega$ $I_D \cong 5.6\text{ A}$, $V_{GEN} = 4.5\text{ V}$, $R_g = 1\text{ }\Omega$	Ch-1		20	30		
			Ch-2		20	30		
Fall Time	t_f		Ch-1		10	15		
			Ch-2		10	15		
Turn-On Delay Time	$t_{d(on)}$	Channel-1 $V_{DD} = 13\text{ V}$, $R_L = 2.3\text{ }\Omega$ $I_D \cong 5.6\text{ A}$, $V_{GEN} = 10\text{ V}$, $R_g = 1\text{ }\Omega$	Ch-1		10	15		
			Ch-2		10	15		
Rise Time	t_r		Ch-1		12	20		
			Ch-2		12	20		
Turn-Off Delay Time	$t_{d(off)}$	Channel-2 $V_{DD} = 13\text{ V}$, $R_L = 2.3\text{ }\Omega$ $I_D \cong 5.6\text{ A}$, $V_{GEN} = 10\text{ V}$, $R_g = 1\text{ }\Omega$	Ch-1		15	25		
			Ch-2		15	25		
Fall Time	t_f		Ch-1		10	15		
			Ch-2		10	15		
Drain-Source Body Diode Characteristics								
Continuous Source-Drain Diode Current	I_S	$T_C = 25\text{ }^{\circ}\text{C}$	Ch-1			2.3	A	
			Ch-2			2.3		
Pulse Diode Forward Current ^a	I_{SM}		Ch-1			30		
			Ch-2			30		
Body Diode Voltage	V_{SD}	$I_S = 5.6\text{ A}$	Ch-1		0.8	1.2	V	
		$I_S = 1\text{ A}$	Ch-2		0.37	0.43		
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 5.6\text{ A}$, $dl/dt = 100\text{ A}/\mu\text{s}$, $T_J = 25\text{ }^{\circ}\text{C}$	Ch-1		15	30	ns	
			Ch-2		15	30		
Body Diode Reverse Recovery Charge	Q_{rr}		$I_F = 5.6\text{ A}$, $dl/dt = 100\text{ A}/\mu\text{s}$, $T_J = 25\text{ }^{\circ}\text{C}$	Ch-1		8	16	nC
				Ch-2		8	16	
Reverse Recovery Fall Time	t_a	$I_F = 5.6\text{ A}$, $dl/dt = 100\text{ A}/\mu\text{s}$, $T_J = 25\text{ }^{\circ}\text{C}$		Ch-1		8.5		ns
				Ch-2		8.5		
Reverse Recovery Rise Time	t_b		Ch-1		6.5			
			Ch-2		6.5			

Notes:

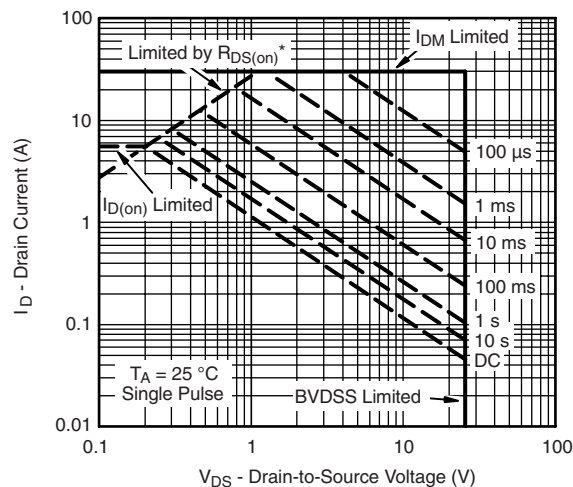
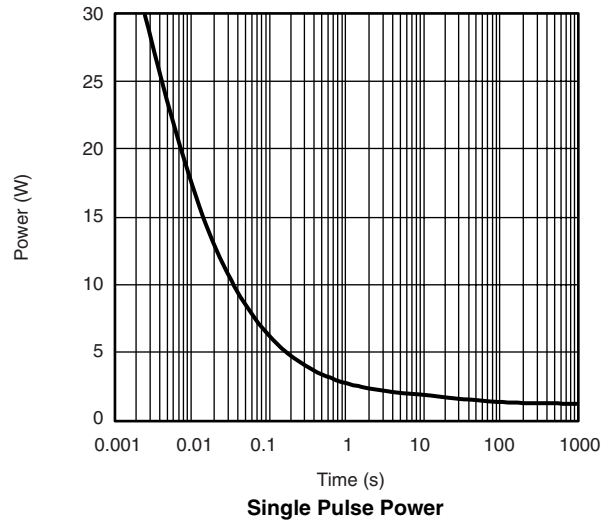
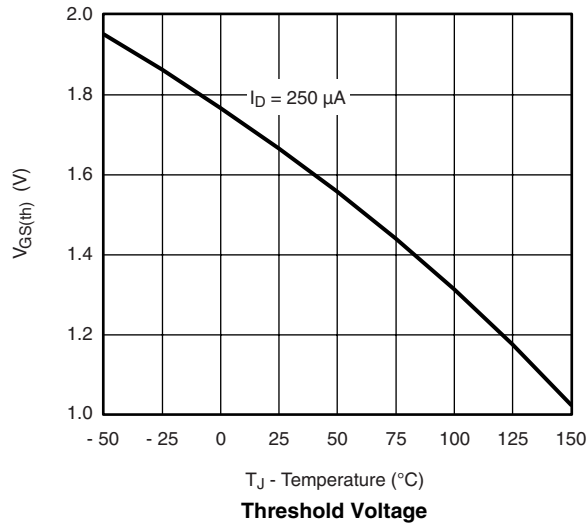
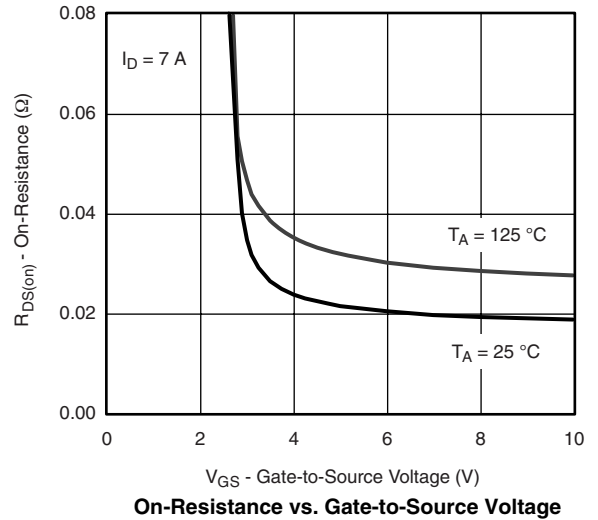
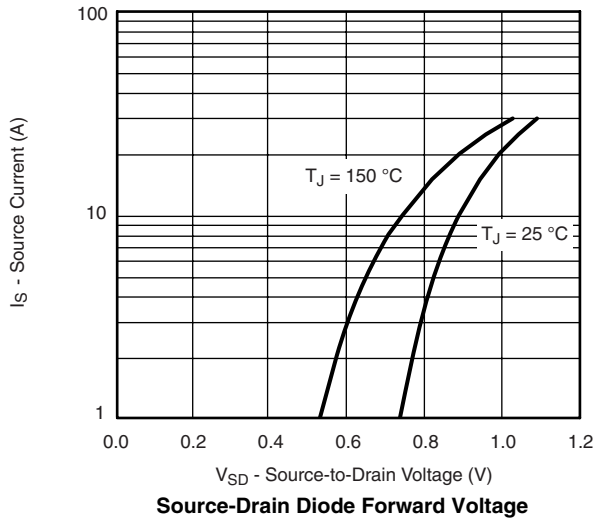
a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

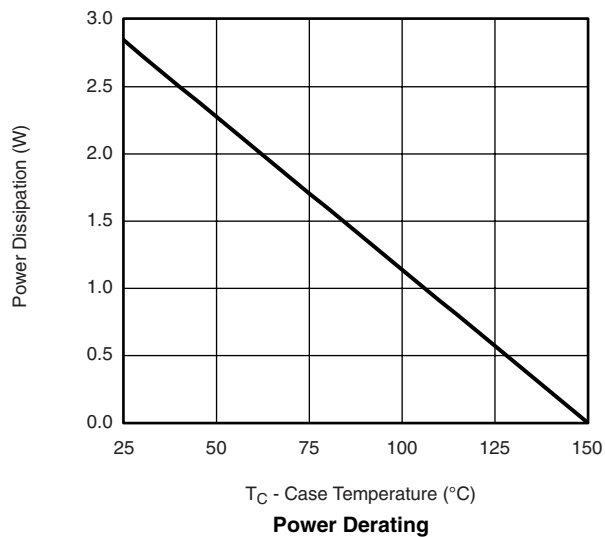
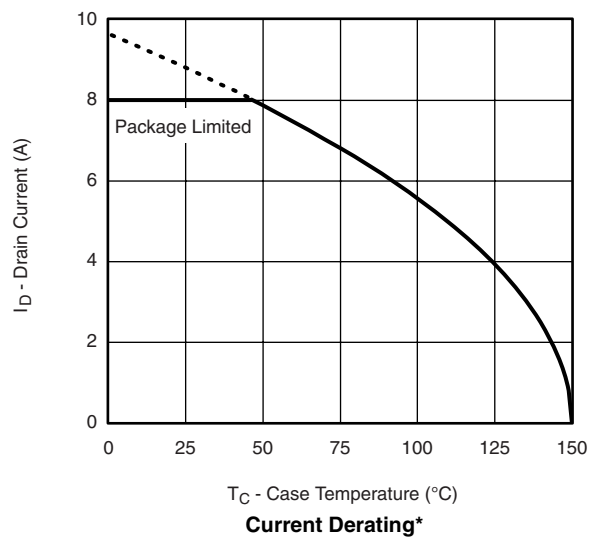
CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted**Output Characteristics****Transfer Characteristics****On-Resistance vs. Drain Current****Capacitance****Gate Charge****On-Resistance vs. Junction Temperature**

CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



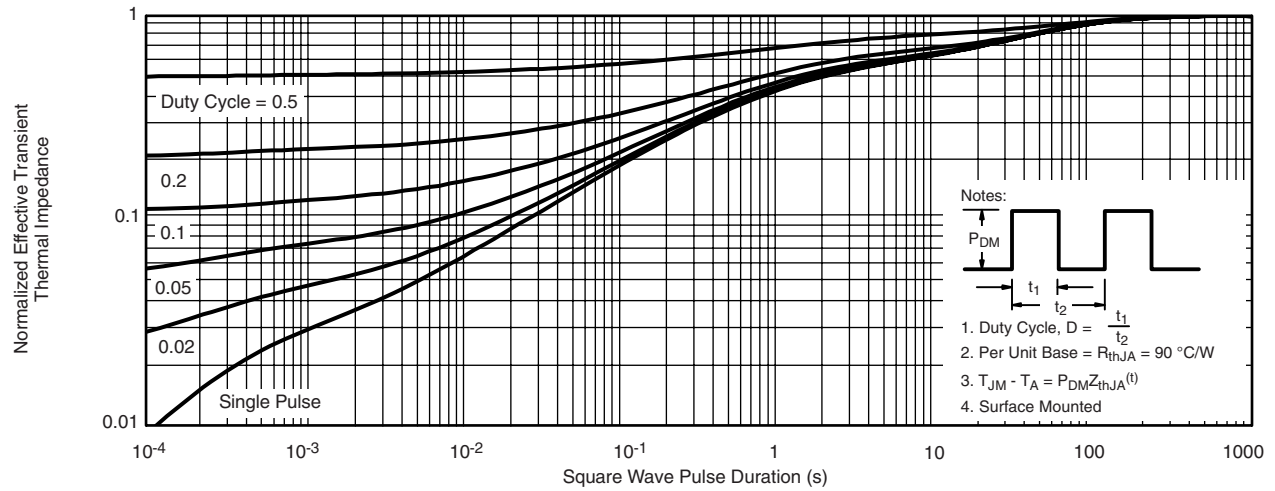
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

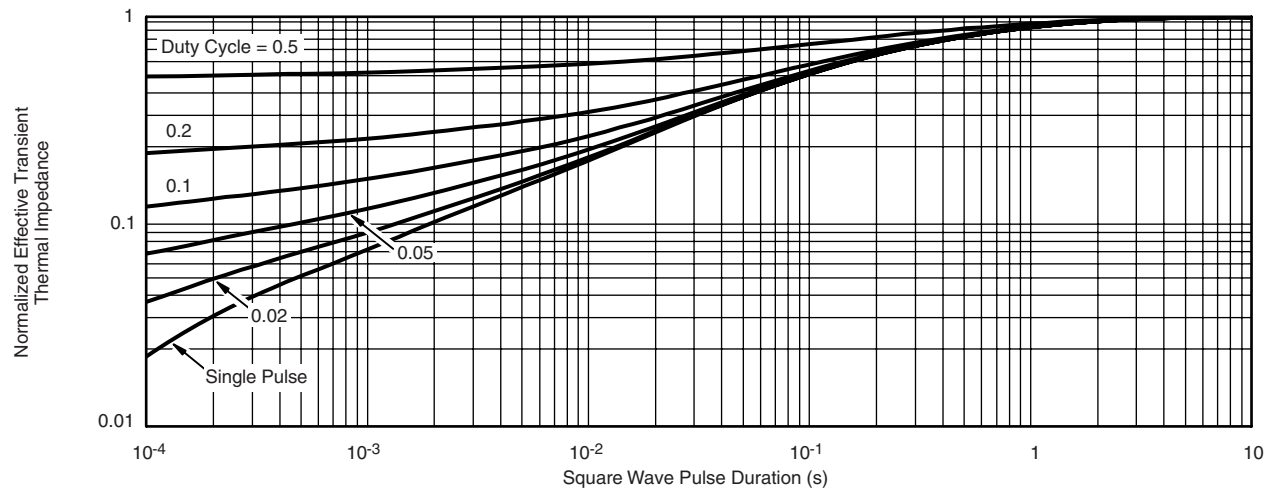
CHANNEL-1 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

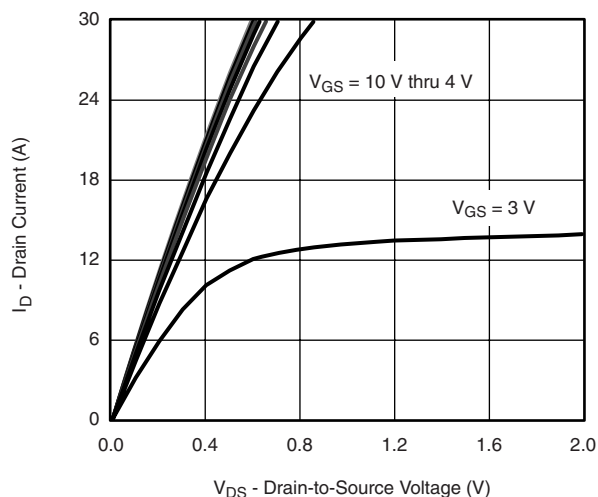
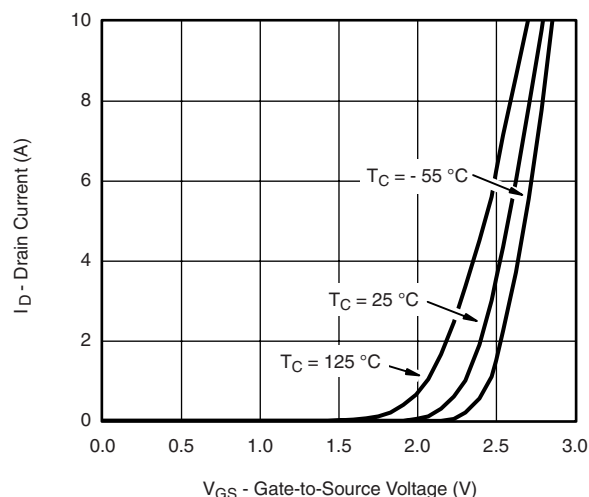
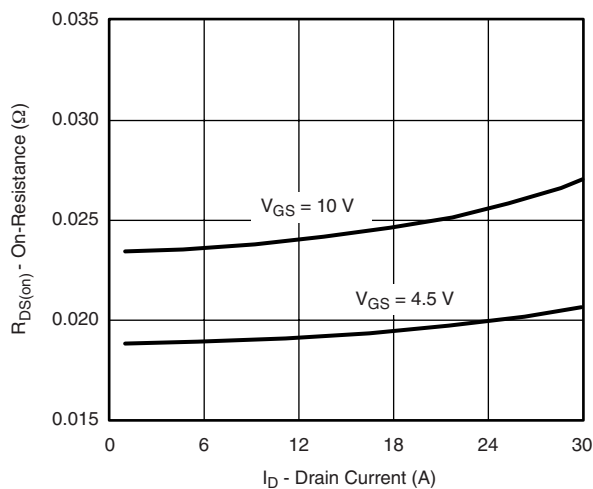
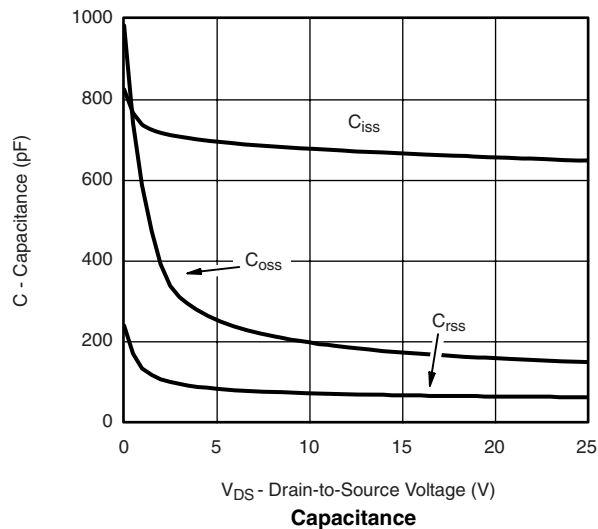
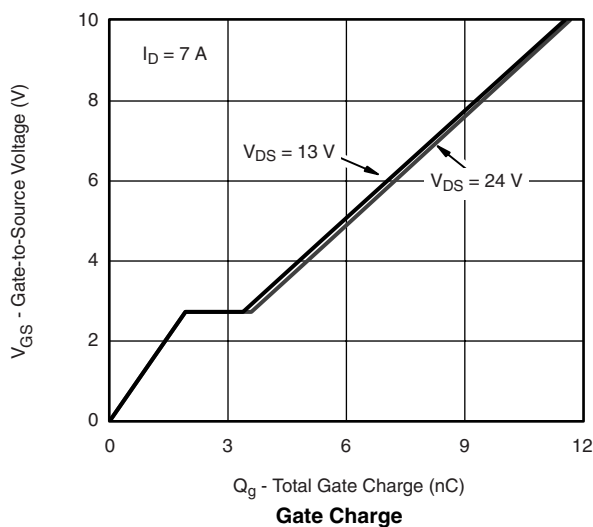
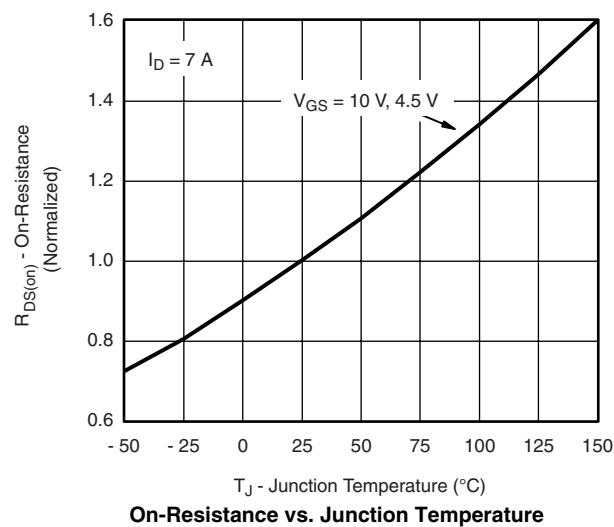
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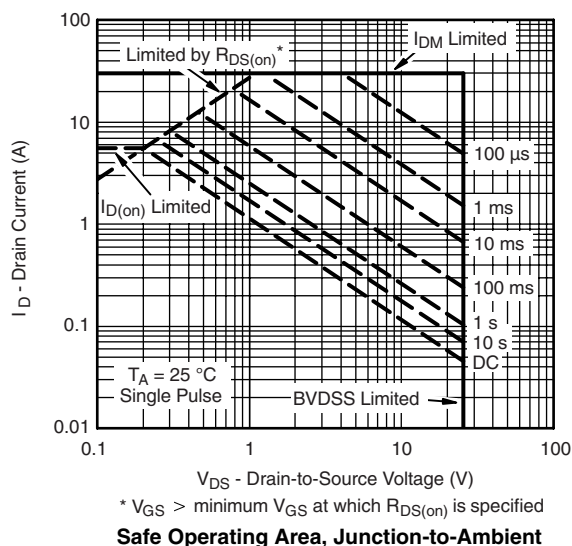
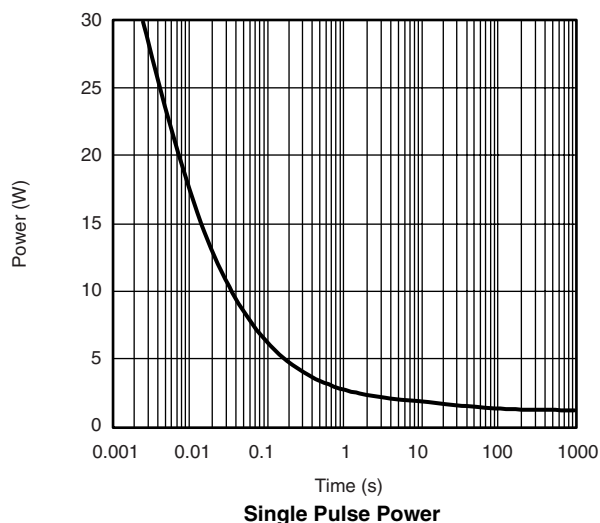
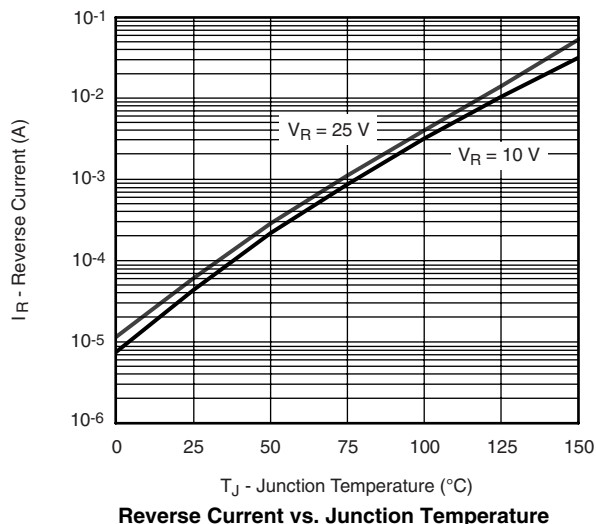
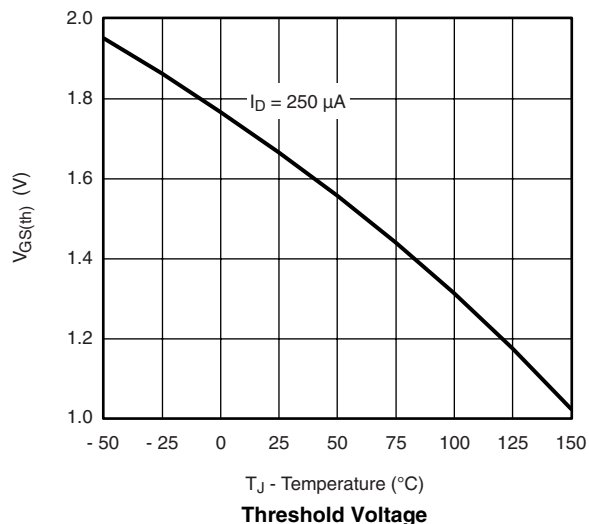
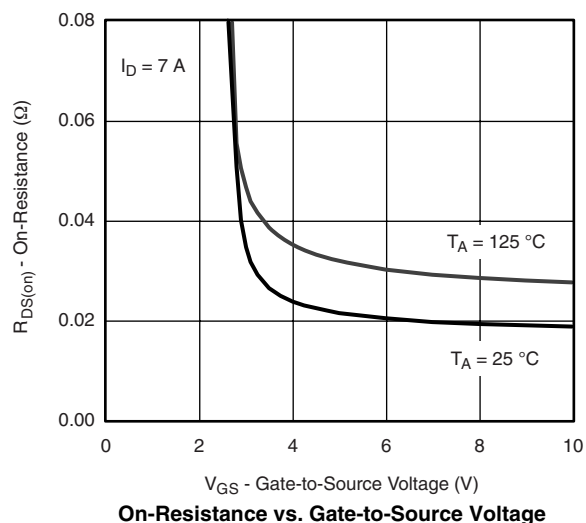
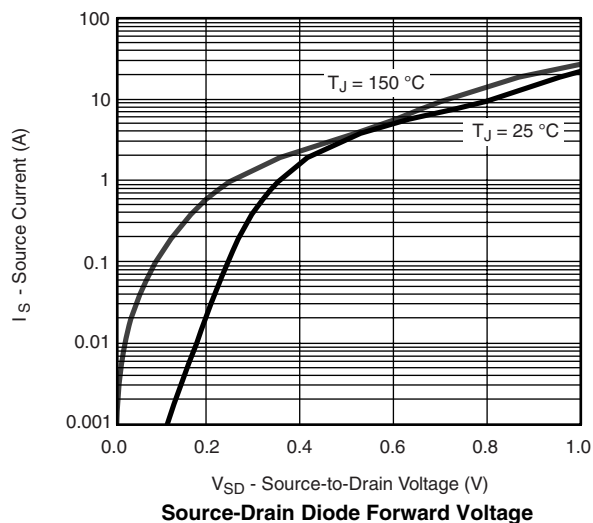
Normalized Thermal Transient Impedance, Junction-to-Ambient

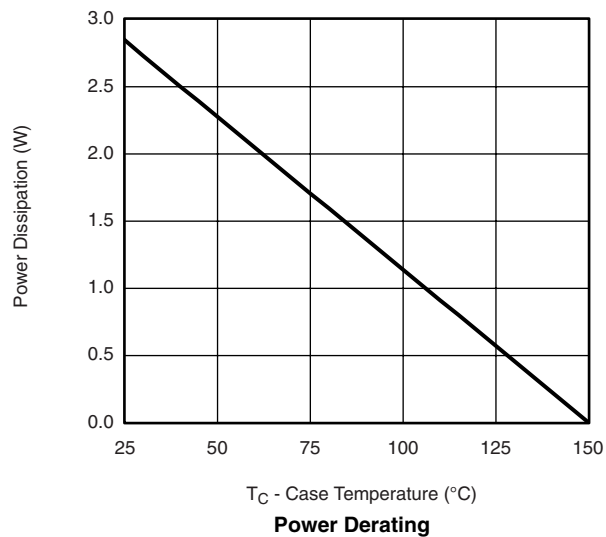
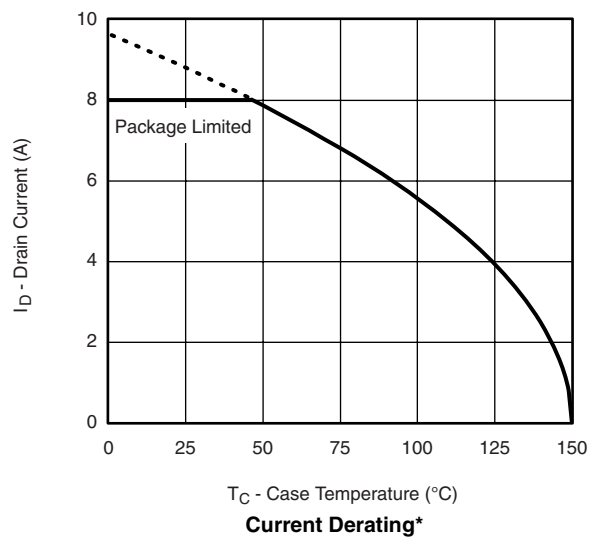


Normalized Thermal Transient Impedance, Junction-to-Foot

CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted**Output Characteristics****Transfer Characteristics****On-Resistance vs. Drain Current****Capacitance****Gate Charge****On-Resistance vs. Junction Temperature**

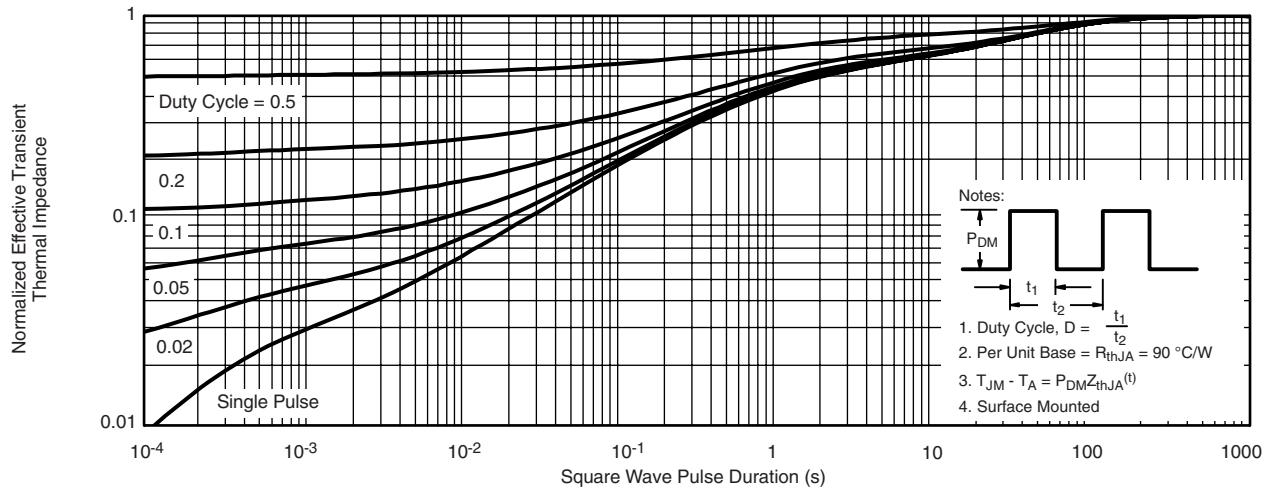
CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



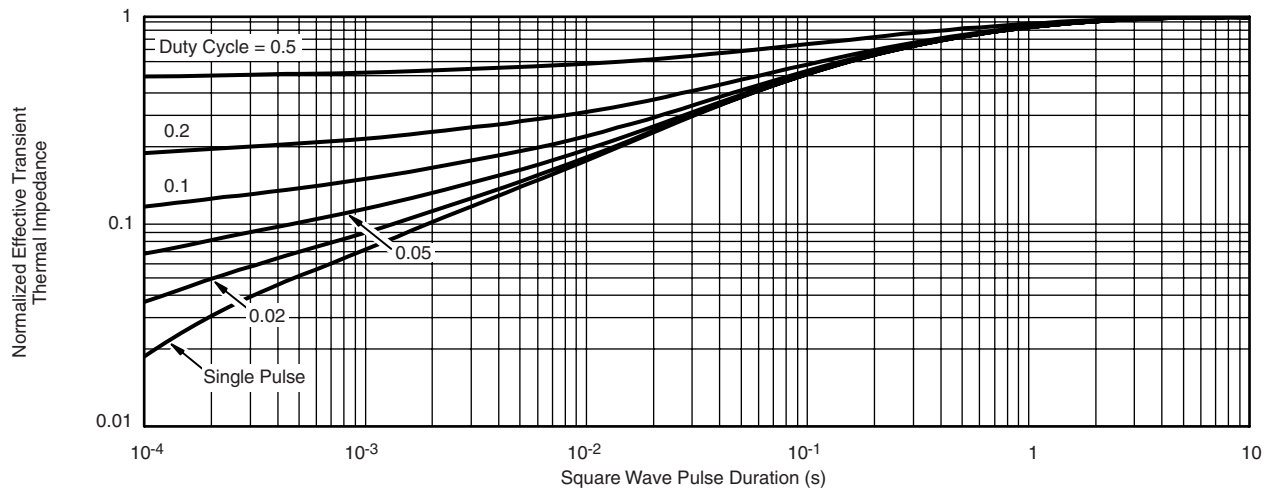
CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

CHANNEL-2 TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient

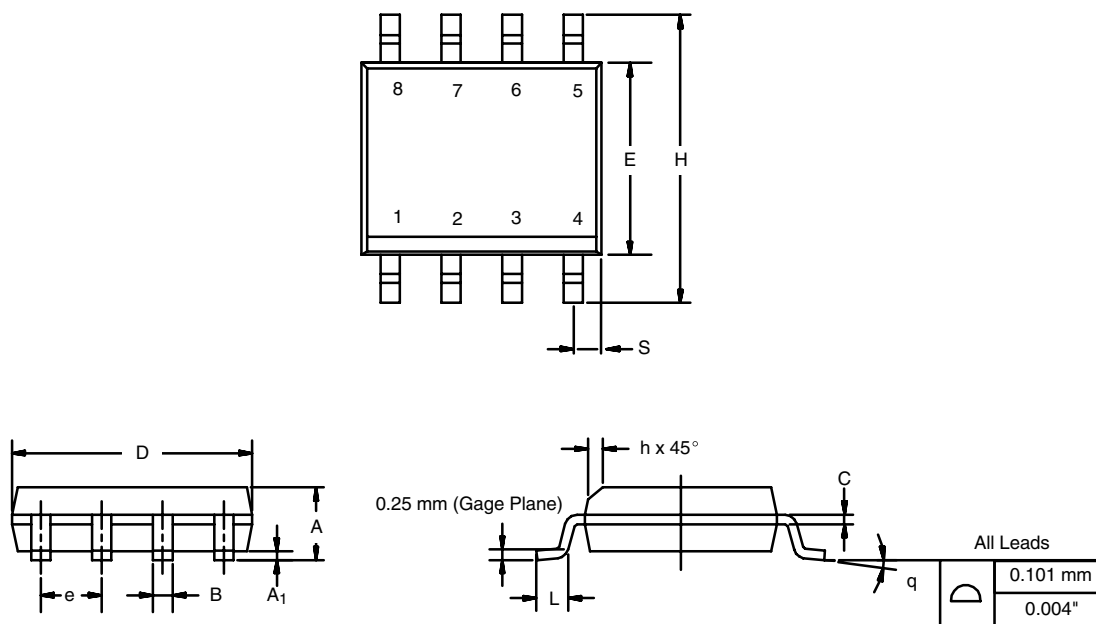


Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?69595.

SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012



DIM	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	1.35	1.75	0.053	0.069
A ₁	0.10	0.20	0.004	0.008
B	0.35	0.51	0.014	0.020
C	0.19	0.25	0.0075	0.010
D	4.80	5.00	0.189	0.196
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.020
L	0.50	0.93	0.020	0.037
q	0°	8°	0°	8°
S	0.44	0.64	0.018	0.026
ECN: C-06527-Rev. I, 11-Sep-06				
DWG: 5498				



Mounting LITTLE FOOT®, SO-8 Power MOSFETs

Wharton McDaniel

Surface-mounted LITTLE FOOT power MOSFETs use integrated circuit and small-signal packages which have been modified to provide the heat transfer capabilities required by power devices. Leadframe materials and design, molding compounds, and die attach materials have been changed, while the footprint of the packages remains the same.

See Application Note 826, *Recommended Minimum Pad Patterns With Outline Drawing Access for Vishay Siliconix MOSFETs*, (<http://www.vishay.com/ppg?72286>), for the basis of the pad design for a LITTLE FOOT SO-8 power MOSFET. In converting this recommended minimum pad to the pad set for a power MOSFET, designers must make two connections: an electrical connection and a thermal connection, to draw heat away from the package.

In the case of the SO-8 package, the thermal connections are very simple. Pins 5, 6, 7, and 8 are the drain of the MOSFET for a single MOSFET package and are connected together. In a dual package, pins 5 and 6 are one drain, and pins 7 and 8 are the other drain. For a small-signal device or integrated circuit, typical connections would be made with traces that are 0.020 inches wide. Since the drain pins serve the additional function of providing the thermal connection to the package, this level of connection is inadequate. The total cross section of the copper may be adequate to carry the current required for the application, but it presents a large thermal impedance. Also, heat spreads in a circular fashion from the heat source. In this case the drain pins are the heat sources when looking at heat spread on the PC board.

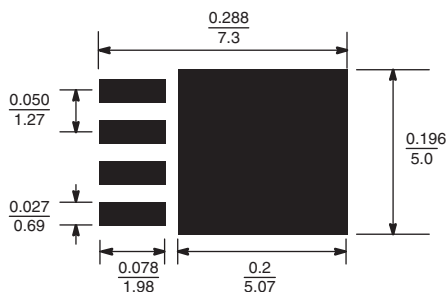


Figure 1. Single MOSFET SO-8 Pad Pattern With Copper Spreading

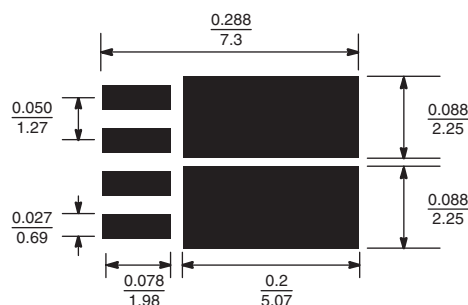


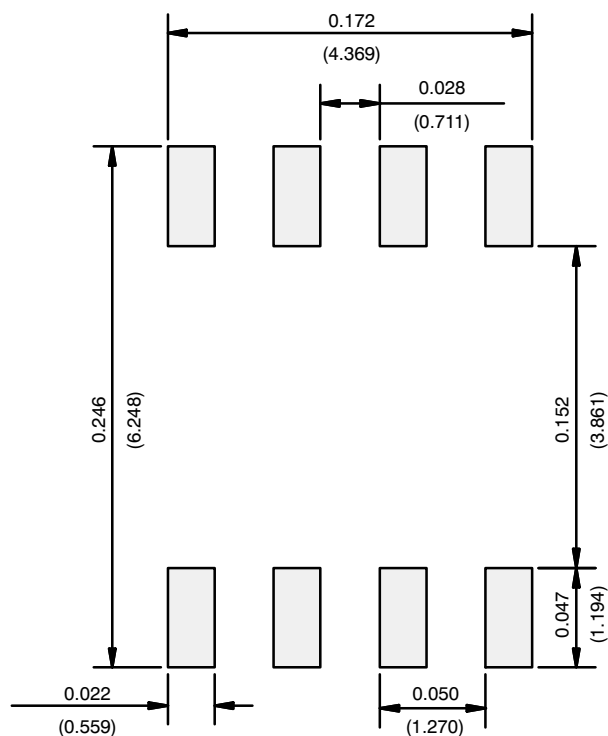
Figure 2. Dual MOSFET SO-8 Pad Pattern With Copper Spreading

The minimum recommended pad patterns for the single-MOSFET SO-8 with copper spreading (Figure 1) and dual-MOSFET SO-8 with copper spreading (Figure 2) show the starting point for utilizing the board area available for the heat-spreading copper. To create this pattern, a plane of copper overlies the drain pins. The copper plane connects the drain pins electrically, but more importantly provides planar copper to draw heat from the drain leads and start the process of spreading the heat so it can be dissipated into the ambient air. These patterns use all the available area underneath the body for this purpose.

Since surface-mounted packages are small, and reflow soldering is the most common way in which these are affixed to the PC board, “thermal” connections from the planar copper to the pads have not been used. Even if additional planar copper area is used, there should be no problems in the soldering process. The actual solder connections are defined by the solder mask openings. By combining the basic footprint with the copper plane on the drain pins, the solder mask generation occurs automatically.

A final item to keep in mind is the width of the power traces. The absolute minimum power trace width must be determined by the amount of current it has to carry. For thermal reasons, this minimum width should be at least 0.020 inches. The use of wide traces connected to the drain plane provides a low impedance path for heat to move away from the device.

RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads
Dimensions in Inches/(mm)

[Return to Index](#)



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